

**SEMICONDUCTOR DEVICES CONTAINING EPOXY MOULDING
COMPOSITIONS AND THE COMPOSITIONS PER SE**

ABSTRACT

A semiconductor device sealed with resin composition and the composition per se, comprising:

(A) a resin,

(B) a resin curing agent,

(C) an inorganic filler comprising aluminum nitride (AlN) and/or silicon oxide (silica) such as aluminum nitride coated with silicon dioxide (silica) which also acts as a flame retardant, and generally

(D) a curing accelerator.